

ABSTRACT

An integrated circuit device package and method of assembling same is disclosed. The device package includes
5 an interposer ring substrate having a hollowed out center mounted on a die attach pad, a die mounted substantially in the center of the die attach pad such that the die is encompassed by the hollowed out center. The package further includes a single-piece drop-in heat sink having a
10 first and second disk shaped portions where the first disk shaped portion has a diameter that is different than the second disk shaped portion.